Bootmode selection can be hard wired if required modes are known.
U6 MUST BE on TOP (OUTER, FREE-AIR) side of board!!!
NOTE: Several components on this page have been removed or changed in the BOM.
OPTIONAL: Heatsink is not needed.

OPTIONAL: to source VDD with the on chip LDO, do not populate R43 and place a 10k resistor on R27. Additionally, the optional components below are not needed.

OPTIONAL: For reduced power consumption use a DC/DC converter instead of the On-Chip Linear Supply. Note: Follow Layout Procedures described in TPS62240 Datasheet.
01 - Title / Notes
02 - Coupling Circuit
03 - USB JTAG/UART
04 - System Power
05 - Connectors

Notes/Revision Information

V0.01 - Initial Release
- Changed C2 value
- Added C2
- Removed 5V rail
- Changed L1, A20 to
- XN, 27 and connected to 3V3
- Removed 5V power supply
- Changed R35 to 1.87k

V0.02 - 10/10/12
- Changed C19, C34 parts
- Changed symbol for M1
- Added multiple pins
- Added C29
- Removed 5V rail
- Changed LD1, LD2 to D6, D7 and connected to 3V3
- Removed 5V power supply
- Changed R35 to 1.87k

V0.03 - 10/18/12
- Changed C23, C24 parts (BOM)
- Changed symbol for M1
- Added multiple pins

V0.04 - 10/22/12
- Updated part U5 symbol

V0.05 - 11/12/12
- Added R6, 2, 7, 4
- Added R26, 61
- Added R34, R35, R36
- Removed J3, J6 and J7

V0.04 - 12/5/12
- Connected M5 to Earth (GND)
- Removed Ground from M64
- Moved TP1 to the other side of R34
- Added Multiple Pins (BOM)

V0.07 - 12/7/12
- Removed TP1 to the other side of R34 (again)

V0.08 - 01/14/13 (R2 Release)
- Updated Part D1 (BOM)

V0.09 - 05/13/13 (R2 Release)
- Changed U1 to 10V
- Added C22 to DNP

V0.10 - 12/5/13 (R2 Release)
- Changed U1 to 10V

V0.11 - 2/24/14 (R5 Release)
- Added U11
- Added C30, C31, C32

V0.12 - 2/24/14 (R5 Release)
- Added U15
- Added C30, C31, C32

TIDC-HYBRID-WMBUS-PLC
Switch Operation:

SW1:
1. ON, SCIB - USB; OFF, JTAG (SCIB EXT)
2. ON, SCIB - USB; OFF, JTAG (SCIB EXT)
3. ON, SCIB - USB; OFF, JTAG (SCIB EXT)

SW2:
1. ON, SCIA-USB; OFF, SCIA-EXT
2. ON, SCIA-USB; OFF, SCIA-EXT
VDDS decoupling capacitors

VDDR decoupling capacitors

Place L331 and C331 close to pin 33. Low inductance ground for C331.
R 1.0.0
- Initial release revision

R1.0.1
L3 -> Changed from LQQ to LQW
L4 -> Changed from LQG to LQW

R1.1.0
- New CC13xx symbol with different DIO to pin mapping
- New Crystal (9 pF, from 7 pF. But 9 pF has been assembled on previous EMs).
- New reference numbers on components.

R1.2.0
- Updating RF filter for better harmonic suppression.
- Remove test point on RXTX pin.

R1.3.0
- For CC1:
  - C15 33pF -> 100pF
  - L12, L21 8.2nH -> 7.5nH
  - C13 4.7nF -> 6.2nF
  - C14 5.2nF -> 3.3nF

R1.3.1
L331 10uH -> 6.8uH

R1.3.2
C341 10uF -> 22uF

R1.3.3
- C331 10uF -> 22uF
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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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